PCN Number:	20180629000.1	PCN Date:	Aug. 1, 2018
Title:	Die Coat Addition for the LM4040B20IDCKR/T		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Nov. 1, 2018	Estimated Sample Availability:	Date provided at sample request

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

This notification is to announce the addition of a die coat for the LM4040B20IDCKR/T:

Current	Proposed
No Die coat	Die coat

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

None

Product Affected:

LM4040B20IDCKR	LM4040B20IDCKT

Qualification Report

LM4040B20IDCKR with Die Coat Yield Improvement Qual - Assembled In 5 leads SC70 package (DCK) at HANA-Thailand

Approve Date 22-June-2018

Product Attributes

Attributes	Qual Device: LM4040B20IDCKR	QBS Product Reference: LM4040B20IDCKR	QBS Product Reference: LM4040C201DBZR	QBS Process Reference: TL4242QKTTRQ1	QBS Package Reference: DG9411DCKR
Assembly Site	HNT	HNT	SHE	NFME	HNT
Package Family	SOT	SOT	SOT	TO-263	SOT
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V 0
Wafer Fab Supplier	SFAB	SFAB	SFAB	SFAB	FFAB
Wafer Process	JI2	JI2	JI2	JI2	ASL3C

- QBS: Qual By Similarity
- Qual Device LM4040B20IDCKR is qualified at LEVEL1-260CG

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM4040B20IDCKR	QBS Product Reference: LM4040B20IDCKR	QBS Product Reference: LM4040C201DBZR	QBS Process Reference: TL4242QKTTRQ1	QBS Package Reference: DG9411DCKR
AC	Autoclave 121C	96 Hours	-	-	-	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/90/0	1/30/0	-	3/90/0	3/90/0
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	3/2400/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-
HBM	ESD - HBM	2500 V	-	-	1/3/0	-	-
HBM	ESD - HBM	1500 V	-	-	-	1/3/0	-
CDM	ESD - CDM	1500 V	-	1/3/0	-	-	-
CDM	ESD - CDM	1000 V	-	-	1/3/0	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 175C	500 Hours	-	-	-	1/45/0	-
HTSL	High Temp. Storage Bake, 150C	1000 cycles	-	-	-	-	3/231/0
LU	Latch-up	(per JESD78)	-	-	1/6/0	1/6/0	-
MQ	Manufacturing (Assembly)	(per mfg. Site specification)	3/Pass	-	-	-	-
PD	Physical Dimensions	-	-	-	-	3/30/0	-
SD	Surface Mount Solderability	Pb	-	-	-	1/15/0	-
SD	Surface Mount Solderability	Pb Free	-	-	-	1/15/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-	-	3/231/0	-
WBS	Ball Bond Shear, Cpk>1.67	Wires	-	-	-	1/30/0	-
YLD	FTY and Bin Summary	-	3/Pass	-	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20171205-124139

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com